

### General Description

The 3N50 have been fabricated using an advanced high voltage MOSFET process that is designed to deliver high levels of performance and robustness in popular AC-DC applications.

### Product Summary

BVDSS	RDS(ON)	ID
500V	3.4Ω	3A

### Applications

- Power factor correction(PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible power supply(UPS)

### TO-252/251 Pin Configuration



### Features

- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DSS}$	Drain-Source Voltage	500	V
$I_D$	Drain Current - Continuous ( $T_C = 25^\circ\text{C}$ )	3	A
	- Continuous ( $T_C = 100^\circ\text{C}$ )	1.5	A
$I_{DM}$	Drain Current - Pulsed	9	A
$V_{GSS}$	Gate-Source Voltage	$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy	65	mJ
$P_D$	Power Dissipation ( $T_C = 25^\circ\text{C}$ )	30	W
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	°C

### Thermal Characteristics

Symbol	Parameter	Rating	Units
$R_{AIC}$	Thermal Resistance, Junction-to-Case Max.	3.57	°C /W
$R_{QJA}$	Thermal Resistance, Junction-to-Ambient Max.	62.5	°C /W

**Electrical Characteristic (T<sub>c</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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**Off Characteristics**

BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250μA	500	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V	--	--	1	uA
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V	--	--	100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -30 V, V <sub>DS</sub> = 0 V	--	--	-100	nA

**On Characteristics**

V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	3	--	5	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1A	--	--	3.4	Ω
G <sub>F</sub>	Forward Transconductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 1A	--	4	--	S

**Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1.0 MHz	--	270	--	pF
C <sub>oss</sub>	Output Capacitance		--	20	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	7	--	pF

**Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 250 V, I <sub>D</sub> = 3A, R <sub>G</sub> = 25Ω	--	30	--	ns
t <sub>r</sub>	Turn-On Rise Time		--	70	--	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		--	55	--	ns
t <sub>f</sub>	Turn-Off Fall Time		--	30	--	ns
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = 400 V, I <sub>D</sub> = 3A, V <sub>GS</sub> = 10 V	--	7	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	3	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	2.5	--	nC

**Drain-Source Diode Characteristics and Maximum Ratings**

I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current	--	--	3	A	
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current	--	--	9	A	
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 3A	--	--	1.4	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 3A, dI <sub>F</sub> / dt = 100 A/us	--	276	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	0.85	--	uC

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